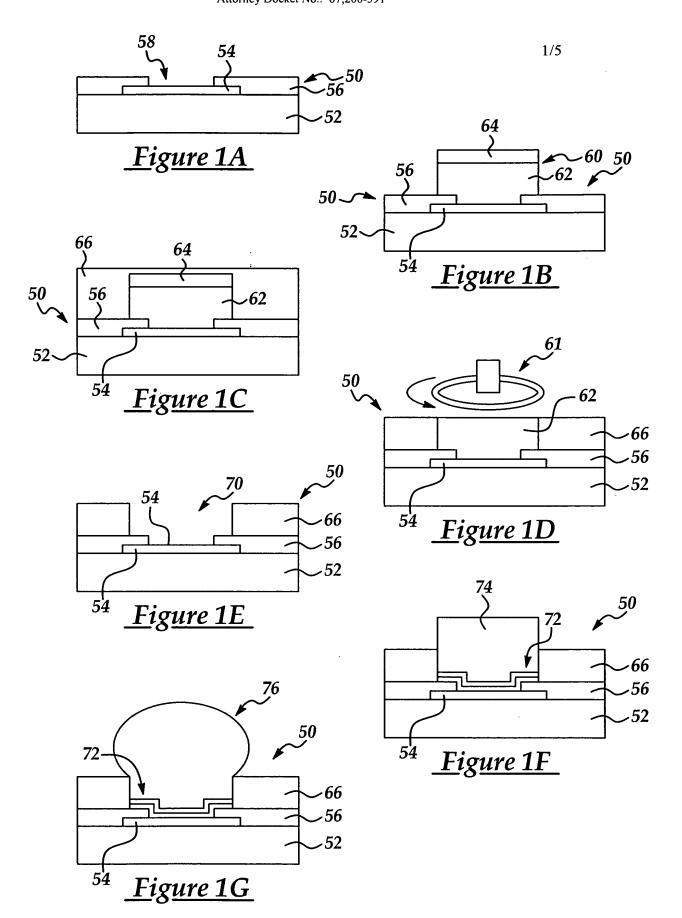
Inventor(s): Lee Serial No.: To Be Assigned Filed: Herewith

For:

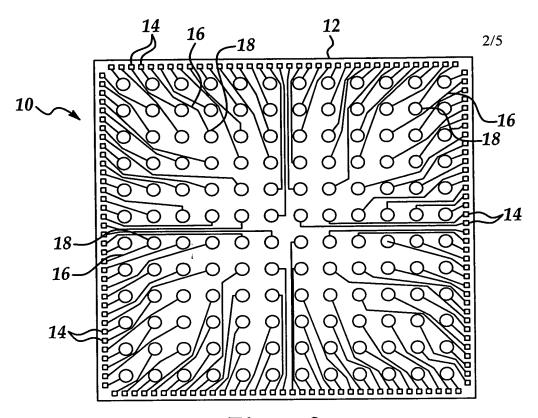
Method of Making a Wafer Level Chip Scale Package Attorney Docket No.: 67,200-591



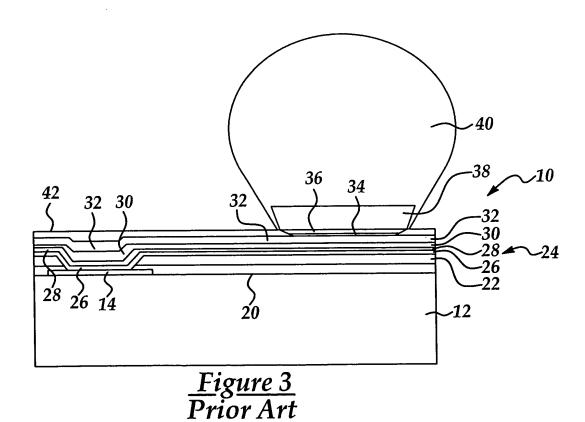
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For:

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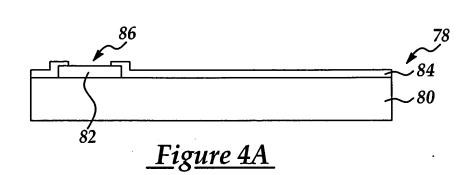
<u>Figure 2</u> Prior Art



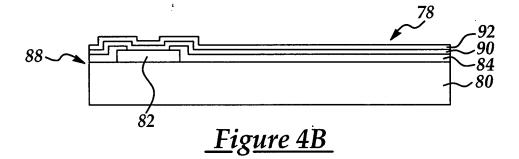


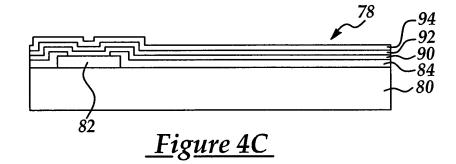
Inventor(s): Lee Serial No.: To Be Assigned Filed: Herewith Method of Making a Wafer Level Chip Scale Package

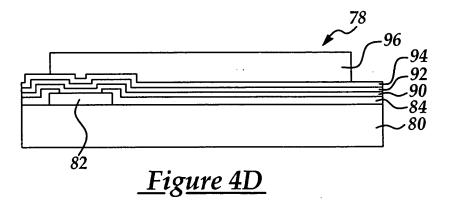
Attorney Docket No.: 67,200-591



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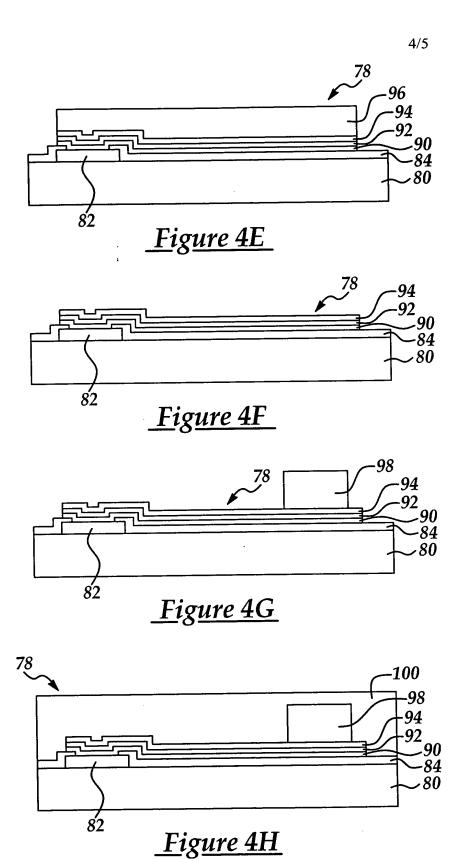




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